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# IRFS450B

#### 500V N-Channel MOSFET

#### **General Description**

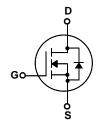
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies, power factor correction and electronic lamp ballasts based on half bridge.

#### **Features**

- 9.6A, 500V,  $R_{DS(on)}$  = 0.39 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 87 nC)
- Low Crss (typical 60 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		IRFS450B	Units
V <sub>DSS</sub>	Drain-Source Voltage		500	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	C)	9.6	Α
	- Continuous (T <sub>C</sub> = 100	)°C)	6.1	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	38.4	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	990	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	9.6	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	9.6	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		96	W
	- Derate above 25°C		0.77	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	3	Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced	I to 25°C		0.55		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V				10	μΑ
		V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			-	100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$		-		-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.8 A		-	0.31	0.39	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_{D} = 4.8 \text{ A}$	(Note 4)		11.5		S
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			2900	3800	pF
C <sub>oss</sub>	Output Capacitance				260	340	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				60	80	pF
Switchi	ing Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 250 \text{ V, } I_{D} = 14 \text{ A,}$ $R_{G} = 25 \Omega$			45	100	ns
t <sub>r</sub>	Turn-On Rise Time				130	270	ns
t <sub>d(off)</sub>	Turn-Off Delay Time				260	530	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4, 5)		125	260	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 14 A,			87	113	nC
Q <sub>gs</sub>	Gate-Source Charge	$V_{GS} = 10 \text{ V}$			13		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)			39		nC
Drain-S	Source Diode Characteristics a	nd Maximum Rating	s				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				9.6	Α	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	ode Forward Current				38.4	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 9.6 \text{ A}$				1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_S = 14 \text{ A,}$ $dI_F / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)			495		ns
Q <sub>rr</sub>	Reverse Recovery Charge				7.66		μС

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 19.3mH,  $I_{AS}$  = 9.6A,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25°C 3.  $I_{SD}$  = 14A, d/dt  $\leq$  300A/µs,  $V_{DD}$   $\leq$  BV $_{DSS}$ , Starting  $T_J$  = 25°C 4. Pulse Test : Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

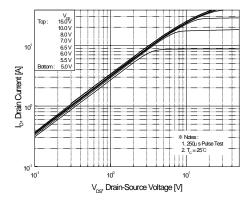


Figure 1. On-Region Characteristics

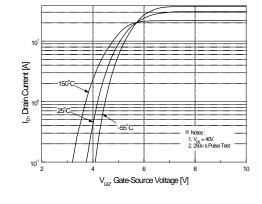


Figure 2. Transfer Characteristics

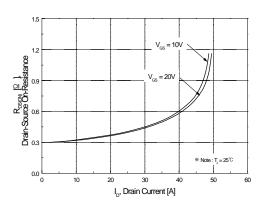


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

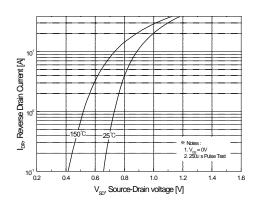


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

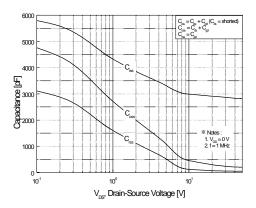


Figure 5. Capacitance Characteristics

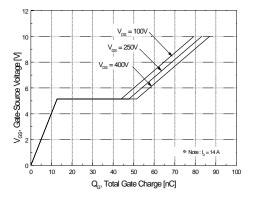


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)

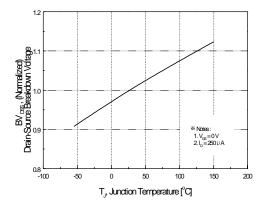
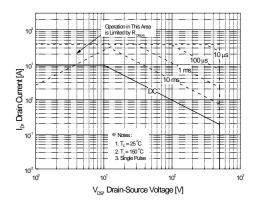


Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



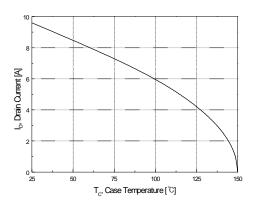


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

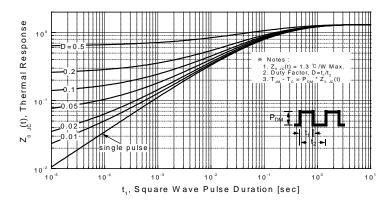
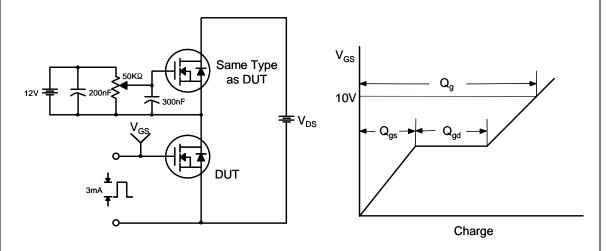
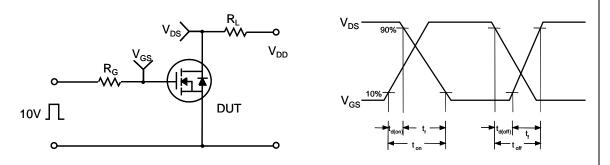


Figure 11. Transient Thermal Response Curve

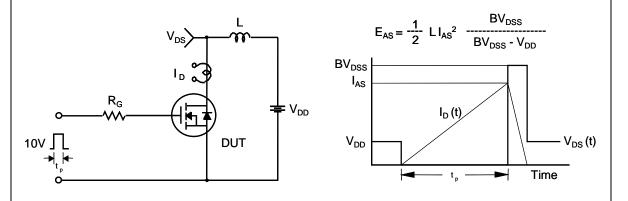
#### **Gate Charge Test Circuit & Waveform**



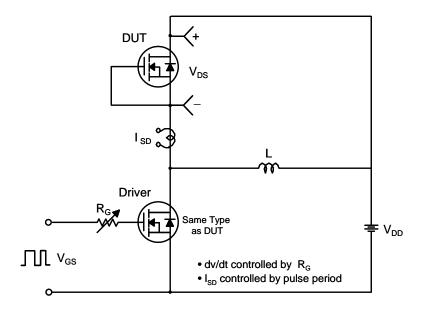
#### **Resistive Switching Test Circuit & Waveforms**

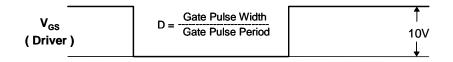


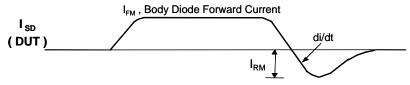
#### **Unclamped Inductive Switching Test Circuit & Waveforms**



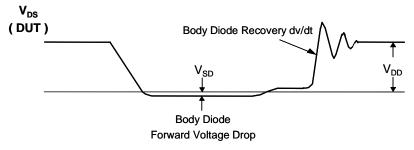
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

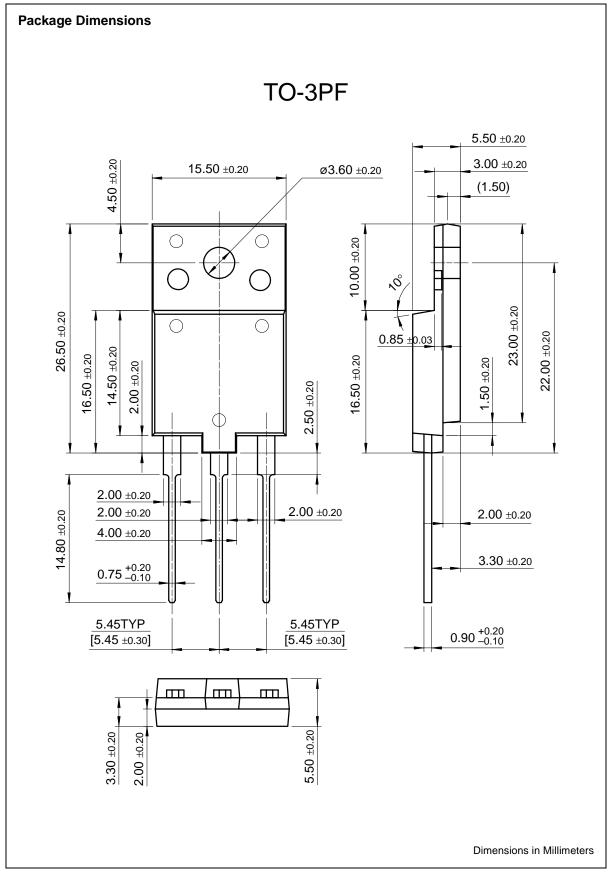






Body Diode Reverse Current





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